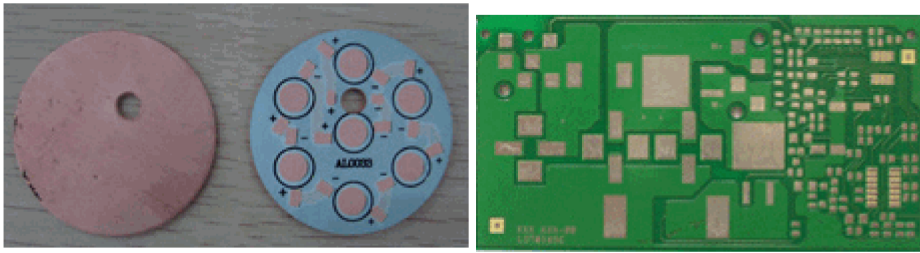


CUAF series



Description and Application

Aluminum base copper-clad laminate have excellent flame retardant, high mechanical strength, dimensional stability etc. Especially it has very good heat sink, electromagnetic shielding and solder float.

It's widely used for the modifier and sparker on fire for motorcycle and mobile, power LED, sound box, power supply module and acoustics shielding system etc.

Note: Chaoshun specializing in the productions of metal base copper-clad Laminates, product has been serialized, Specification complete, the copper substrate type4: CUAF-01-R, CUAF-04-A, CUAF-05, CUAF-06, sheet copper thickness1.0mm,1.5mm,2.0mm, art models: Brase, copper, copper foil thickness is 18um,35um,105um,140um. Surface size: 375mm×330mm; 600mm×500mm.

Test base:

Thickness copper: 35 um

Cu base: 1.0mm

Test result:

Test item		Company	CUAF-01-R	CUAF-04-A	CUAF-05	CUAF-06
			Test results	Test results	Test results	Test results
Peel Strength	Normal behavior A	N/mm	2.0	1.7	1.5	1.4
	After thermal stress		1.8	1.5	1.3	1.2
Blister test After Thermal stress		/	(260°C, 2min) No slice, No blister	(288°C, 2min) No slice, No blister	(288°C, 2min) No slice, No blister	(300°C, 2min) No slice, No Blister
Thermal resistance		°C/W	1.0	0.65	0.45	0.4
Thermal-conductive Factor		W/m·k	1.0	1.5	2.2	2.5
Flammability (A)		/	FV-0	FV-0	FV-0	FV-0
Surface Resistivity	Normal behavior A	MΩ	5×10^7	5×10^7	3.68×10^7	3.5×10^7
	Constant damp heat (25 degrees to 65 degrees c., RH:90%~98%, 20cycles after)		2×10^6	4.5×10^6	3.39×10^6	4.5×10^6
Volume Resistivity	Normal behavior A	MΩ·m	4×10^8	1.0×10^8	4.2×10^8	4.2×10^8
	Constant damp heat (25 degrees to 65 degrees c., RH:90%~98%, 20cycles after)		5×10^7	1.9×10^7	3.17×10^7	3.17×10^7
Breakdown voltage AC (5mA leakage current)		KV	6	4	6	6
Dielectric constant (1MHZ) (40°C, 93%, 96h)		/	4.2	4.2	4.24	4.2
Dielectric loss factor (1MHZ) (40°C, 93%, 96h)		/	0.02	0.02	0.033	0.033
CTI		V	230	600	600	600